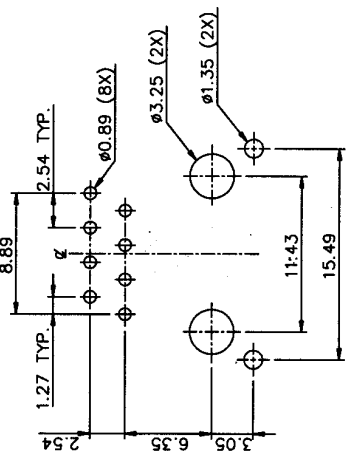
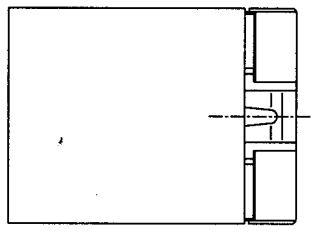


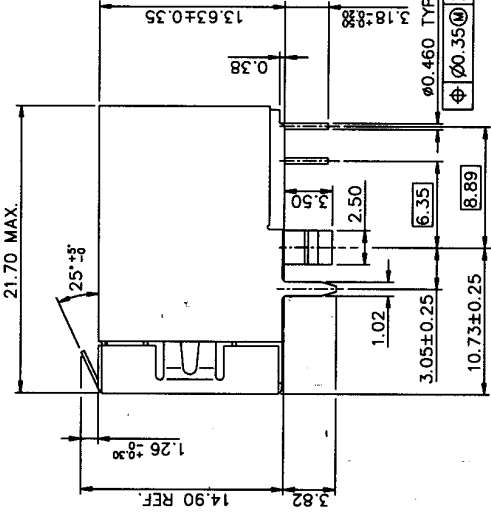
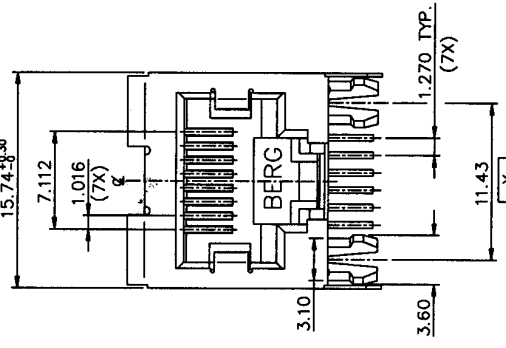
1 2 3 4 5 6

PRODUCT NO.
74523-001N
-001NF

LEAD FREE PRODUCT NO.



RECOMMENDED PCB LAYOUT



- NOTES:
1. RECOMMENDED P.C.B THICKNESS 1.60 MM
 2. HOUSING MAT'L: HIGH TEMP RESIN.
 3. CONTACTS: PHOS BRONZE ALLOY UNS-C51000, $\phi 0.460$ ROUND WIRE, PLATING SEE TABLE.
 4. SHIELDING MATERIAL: 0.25MM THICK, COPPER ALLOY. SHIELDING PLATING: 30 μ MIN. NICKEL PLATED.
 5. PACKAGING: USING TRAY.
 6. PART NO. DESCRIPTIONS:
74523 - X 01 N
SHIELDING PLATING:
FOR 30 μ NICKEL PLATING ONLY.
PORT NUMBERS
PLATING CODE:
0=0.76 μ m/30 μ " GXT
 7. THIS PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008.
 8. THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.60mm MINIMUM THICK CIRCUIT BOARD.
 9. IF LF P/N PACKAGING MEETS GS-14-920 SPECIFICATION.

mat'l code		tolerance unless otherwise specified		CUSTOMER COPY		FCJ	
rev.	ec'n no.	no.	dr	date	linear	angular	projection
A	180-318	www	L	07/21/98	0.00 ± 0.30	0.00 ± 0.15	0
B	103-0443	W	L	10/06/03	0.000 ± 0.10	± 2°	0
C	105-0002	YS		07/21/05	dr	SATHY LN	12/03/97
D	105-0016	YS		07/21/05	engr	TONY CHEN	12/03/97
sheet/revision		D		app'd/JENN TSAO		12/03/97	
index	sheet	1	1				

title	product family	MOD JACK	code
R/A CAT 5 MOD JACK 8 POS. SPECIALLY SHIELDED SNAP REG			
size	dwg no.		
unit			
scale	3 : 1		
sheet	74523		
of	1 of 1		

STATUS:Released Printed: Mar 10, 2002

PDM: Rev:D

Printed: Aug 01, 2010



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